

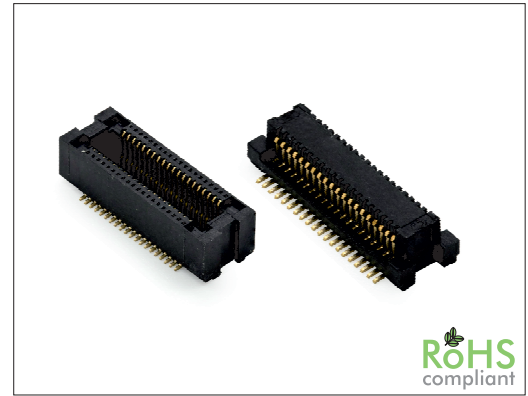
1052 Series

0.50 mm Micro Board to Board

General specifications

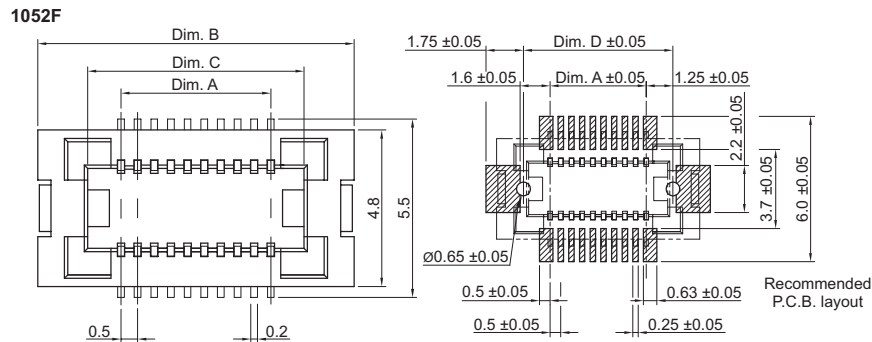
Insulator material	Glass filled polyamide, UL94V-0, color: black
Contact material	Copper alloy
Current rating	0.5 A
Voltage rating	50 VAC
Contact resistance	50 mΩ max.
Insulator resistance	500 MΩ @ 500 VDC
Dielectrical withstanding	500 VAC for 1 min
Operating temperature	-40 °C to +105 °C
Soldering	JEDEC lead free reflow soldering process

Mating parts series



Mechanical dimensions

Unit: mm

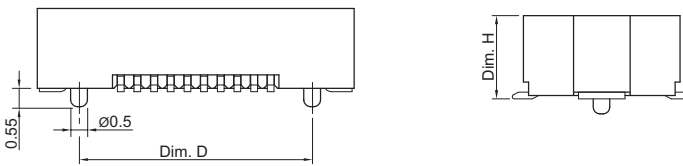


$$\text{Dim. A} = \left(\frac{\text{No. of contacts}}{2} - 1 \right) \times 0.50$$

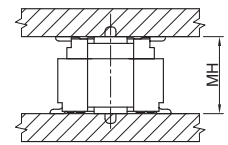
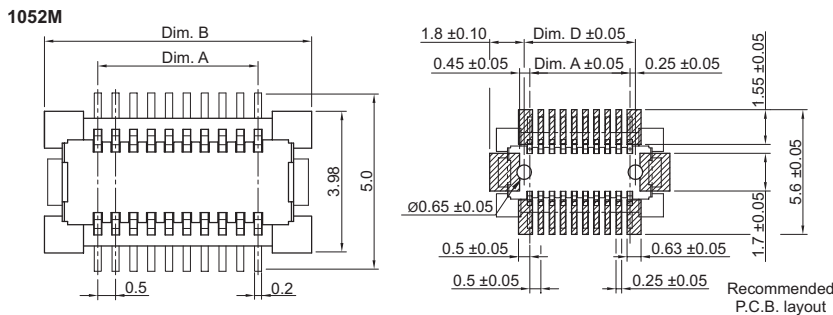
$$\text{Dim. B} = \text{Dim. A} + 5.00$$

$$\text{Dim. C} = \text{Dim. A} + 2.00$$

$$\text{Dim. D} = \text{Dim. A} + 2.50$$



Mating height variations		
Part no.	1052M-xxB-200	1052M-xxB-300
1052F-xxB-200	2.50	N/A
1052F-xxB-250	3.00	3.50
1052F-xxB-300	N/A	4.00
1052F-xxB-400	4.50	5.00



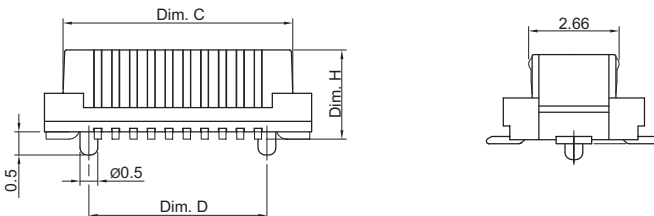
1052F + 1052M
Mating height (MH) 2.50 to 5.00 mm

$$\text{Dim. A} = \left(\frac{\text{No. of contacts}}{2} - 1 \right) \times 0.50$$

$$\text{Dim. B} = \text{Dim. A} + 3.00$$

$$\text{Dim. C} = \text{Dim. A} + 2.00$$

$$\text{Dim. D} = \text{Dim. A} + 0.50$$



Tolerances		
Linear	X	± 0.30
	XX	± 0.20
	XXX	± 0.10

Part numbering guide

1052 F	10	B	200	R
Series F = SMT female M = SMT male	No. of contacts 10 to 80	Contact plating B = Flashgold	1052F Dim. H 200 = 2.00 mm 250 = 2.50 mm 300 = 3.00 mm 400 = 4.00 mm	1052M Dim. H 200 = 2.00 mm 300 = 3.00 mm Packing R = Reel

* standard

